

Title (en)  
INKJET DEVICE ENCAPSULATED AT THE WAFER SCALE

Title (de)  
INKJET-EINRICHTUNG, DIE AUF DEM WAFER-MASSSTAB VERKAPSELT IST

Title (fr)  
DISPOSITIF A JET D'ENCRE ENCAPSULE A L'ECHELLE DE LA TRANCHE

Publication  
**EP 1356508 A1 20031029 (EN)**

Application  
**EP 02729358 A 20020108**

Priority

- AU 0200014 W 20020108
- AU PR245401 A 20010110

Abstract (en)  
[origin: US2004080566A1] Micro-fabricated devices (152) is packaged at the wafer (150) stage with a cap (156, 160) applied to one or both sides of the wafer (150) prior to separation of the wafer into separate devices. The cap (156) on the top side overlays the respective device(s) (152), except the bond pads (158). The cap (160) on the bottom overlays all of the respective device(s) (152).

IPC 1-7  
**H01L 21/52**; B81B 7/04; B81C 1/00; B41J 2/16; H01S 5/022

IPC 8 full level  
**H01L 23/02** (2006.01); **B41J 2/04** (2006.01); **B41J 2/14** (2006.01); **B41J 2/16** (2006.01); **B81B 7/00** (2006.01); **H01L 23/04** (2006.01)

CPC (source: EP US)  
**B41J 2/04** (2013.01 - EP US); **B41J 2/14427** (2013.01 - EP US); **B41J 2/1623** (2013.01 - EP US); **B41J 2/1628** (2013.01 - EP US); **B41J 2/1629** (2013.01 - EP US); **B41J 2/1635** (2013.01 - EP US); **B41J 2/1637** (2013.01 - EP US); **B41J 2/1648** (2013.01 - EP US); **B81B 7/0061** (2013.01 - EP US); **B41J 2002/14419** (2013.01 - EP US); **B41J 2002/14443** (2013.01 - EP US); **B41J 2002/14491** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48465** (2013.01 - EP US)

C-Set (source: EP US)

1. **H01L 2224/48091 + H01L 2924/00014**
2. **H01L 2224/48465 + H01L 2224/48091 + H01L 2924/00**

Designated contracting state (EPC)  
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)  
**US 2004080566 A1 20040429**; **US 6923524 B2 20050802**; AU PR245401 A0 20010201; EP 1356508 A1 20031029; EP 1356508 A4 20070502; JP 2004520706 A 20040708; JP 3963837 B2 20070822; US 2002089569 A1 20020711; US 6557978 B2 20030506; WO 02056360 A1 20020718

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